

0012490818

WPI Acc no: 2002-438219/

XRAM Acc no: C2002-124643

XRPX Acc No: N2002-344927

Thermally conductive sheet for light source, comprises silicone rubber, and specific amounts of electric insulation heat conduction filler, and graphitized carbon fiber and has preset volume resistivity

Patent Assignee: FUJI POLYMATECH CO LTD (FUJI-N)

Inventor: YAMAZAKI

Patent Family (1 patents, 1 countries)

Patent Number	Kind	Date	Application Number	Kind	Date	Update	Type
JP 2002003717	A	20020109	JP 2000186193	A	20000621	200247	B

Priority Applications (no., kind, date): JP 2000186193 A 20000621

Patent Details

Patent Number	Kind	Lan	Pgs	Draw	Filing Notes
JP 2002003717	A	JA	7	4	

Alerting Abstract JP A

NOVELTY - The thermally conductive sheet (1) comprises silicone rubber, 5-40 volume% of graphitized carbon fiber and 30-50 volume% of electric insulation heat conduction filler, and has a volume resistivity of more than 10^6 ohm.cm.

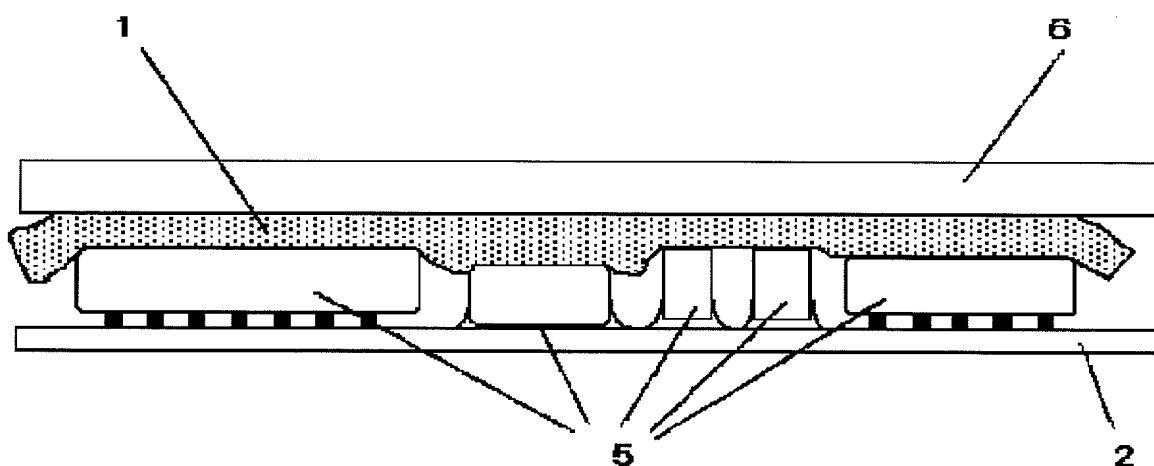
USE - For a semiconductor elements of an electric product, power supply, light source, metal forming goods, such as injection and extrusion molding goods, and compression molded product.

ADVANTAGE - The thermally conductive sheet has high thermal conductivity, excellent electric insulation. The semiconductor device operates normally, without generating electric damage, using thermally conductive sheet.

DESCRIPTION OF DRAWINGS - The figure shows the semiconductor device, which uses thermally conductive sheet.

1Thermally conductive sheet

Main Drawing Sheet(s) or Clipped Structure(s)



Title Terms /Index Terms/Additional Words: THERMAL; CONDUCTING; SHEET; LIGHT; SOURCE; COMPRISE; SILICONE; RUBBER; SPECIFIC; AMOUNT; ELECTRIC; INSULATE; HEAT; FILL; GRAPHITISE; CARBON; PRESET; VOLUME; RESISTOR

Class Codes

International Patent Classification

IPC	Class Level	Scope	Position	Status	Version Date
C08L-083/04			Main		"Version 7"
C08J-005/18; C08K-003/00; C08K-007/06; C09K-005/08			Secondary		"Version 7"

File Segment: CPI; EPI

DWPI Class: A26; A85; E36; U11

Manual Codes (EPI/S-X): U11-A07

Manual Codes (CPI/A-N): A06-A00E2; A08-M09C; A08-R03A; A09-A01A; A12-E07C; E31-N04D

Original Publication Data by Authority

Japan

Publication No. **JP 2002003717 A (Update 200247 B)**

Publication Date: 20020109

HEAT CONDUCTIVE SHEET

Assignee: POLYMATECH CO LTD (FUJI-N)

Inventor: YAMAZAKI JUN

Language: JA (7 pages, 4 drawings)

Application: JP 2000186193 A 20000621 (Local application)

Original IPC: C09K-5/08(-) C08L-83/04(A) C08J-5/18(B) C08K-3/00(B) C08K-7/06(B)

Current IPC: C09K-5/08(-) C08L-83/04(A) C08J-5/18(B) C08K-3/00(B) C08K-7/06(B)